



7. Cured Epoxy Resin

Instrument: Tritec 2000 Dynamic Mechanical Analyser

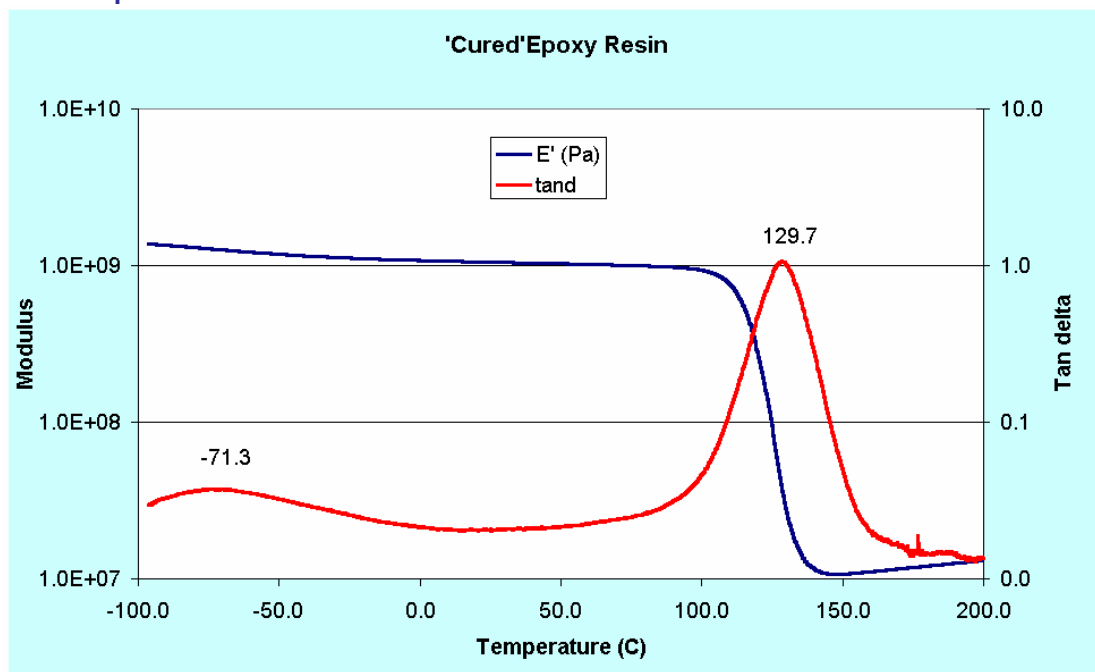
Sample: Epoxy Resin

Geometry: Single Cantilevered Bending

%RMS strain: 0.080

Frequencies (Hz): 1.0

Thermal profile: 2°C/minute to 200°C



Comments:

Note that this material is showing signs of 'post curing' after the Tg and that the modulus at room temperature would be expected to rise again as a result of 'post curing'.

The relaxation at -71°C is the beta transition for the resin (x link relaxation).

The alpha transition at 129.7°C is the main chain relaxation and in this case is likely to increase in temperature with post curing.